

MODIFICATION RECOMMENDED

E7515A-01

S E R V I C E N O T E

Supersedes:
NONE

E7515A UXM Wireless Test Set

Serial Numbers: TH53460050 / TH54250356

Modify The Embedded PC To Improve Boot Reliability

Parts Required:

P/N	Description	Qty.
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NONE

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION:		
MODIFICATION RECOMMENDED		
ACTION <input type="checkbox"/> ON SPECIFIED FAILURE CATEGORY: <input checked="" type="checkbox"/> AGREEABLE TIME		STANDARDS LABOR: 1.0 Hours
LOCATION <input type="checkbox"/> CUSTOMER INSTALLABLE CATEGORY: <input type="checkbox"/> ON-SITE (active On-site contract required) <input checked="" type="checkbox"/> SERVICE CENTER <input type="checkbox"/> CHANNEL PARTNER	SERVICE <input type="checkbox"/> RETURN INVENTORY: <input type="checkbox"/> SCRAP <input checked="" type="checkbox"/> SEE TEXT	USED <input type="checkbox"/> RETURN PARTS: <input type="checkbox"/> SCRAP <input checked="" type="checkbox"/> SEE TEXT
AVAILABILITY: PRODUCT'S SUPPORT LIFE		NO CHARGE AVAILABLE UNTIL: 02-FEBRUARY-2018
<input type="checkbox"/> Calibration Required <input checked="" type="checkbox"/> Calibration NOT Required		PRODUCT LINE: 13 AUTHOR: FC
ADDITIONAL INFORMATION: This modification does not impact service inventory. This modification does not require the removal or disposal of any parts.		

Situation:

The E7515A will fail to boot if either of the RAM modules on the Embedded PC is not fully engaged in the memory slot.

A design change to prevent this from happening has been implemented on every instrument from serial number TH54250357 onwards.

Solution/Action:

Remove the outer covers from the instrument and inspect the RAM modules on the Embedded PC.

If the RAM modules have been secured with thermal glue (as shown in Figure 1), then this service note does not apply – the modification has already been implemented.



Figure 1

If the RAM modules have not been secured with thermal glue, then ensure they are both fully engaged and locked in their memory slots (as shown in Figure 2).

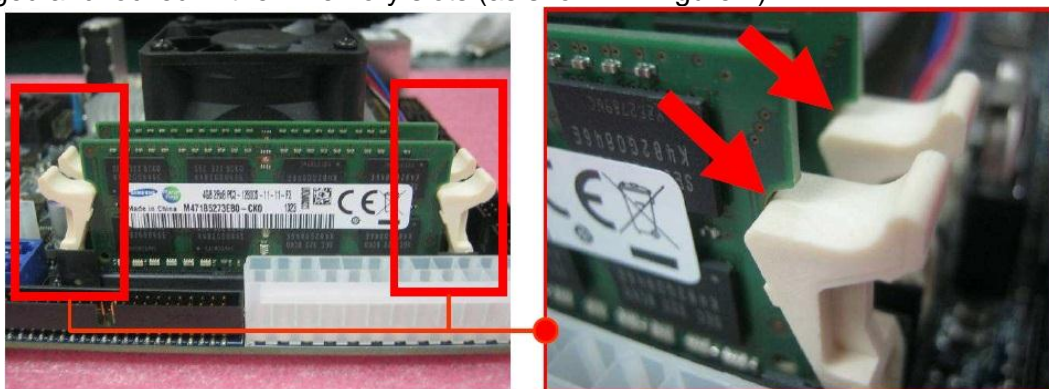


Figure 2

Carefully apply thermal glue as indicated in Figure 1. Wait for the glue to harden before re-assembling the instrument.

The following thermal glue is recommended, but similar alternatives can also be used:

Description : Power Adhesives Transparent 12mm Hot Melt Glue Stick

Mfr. Part No. : 232-12-200-CRP-CP08-RS

Revision History:

Service Note Revision	Date	Author	Reason For Change
01	Feb-2015	FC	As published